

# NTMFS4982NF

## Power MOSFET

30 V, 207 A, Single N-Channel, SO-8 FL

### Features

- Integrated Schottky Diode
- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- These Devices are Pb-Free and are RoHS Compliant

### Applications

- Server, Netcom, POL
- Synchronous Rectification for DC-DC Converters
- Low Side Switching
- High Performance Applications

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Symbol	Value	Unit		
Drain-to-Source Voltage	$V_{DSS}$	30	V		
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V		
Continuous Drain Current $R_{\theta JA}$ (Note 1)	$I_D$	$T_A = 25^\circ\text{C}$	36	A	
		$T_A = 85^\circ\text{C}$	26		
Power Dissipation $R_{\theta JA}$ (Note 1)	$P_D$	$T_A = 25^\circ\text{C}$	2.7	W	
		$T_A = 85^\circ\text{C}$			
Continuous Drain Current $R_{\theta JA} \leq 10$ sec	$I_D$	$T_A = 25^\circ\text{C}$	60	A	
		$T_A = 85^\circ\text{C}$	43		
Power Dissipation $R_{\theta JA}, t \leq 10$ sec	$P_D$	$T_A = 25^\circ\text{C}$	7.4	W	
		$T_A = 85^\circ\text{C}$			
Continuous Drain Current $R_{\theta JA}$ (Note 2)	$I_D$	$T_A = 25^\circ\text{C}$	26.5	A	
		$T_A = 85^\circ\text{C}$	19		
Power Dissipation $R_{\theta JA}$ (Note 2)	$P_D$	$T_A = 25^\circ\text{C}$	1.5	W	
		$T_C = 25^\circ\text{C}$			
Continuous Drain Current $R_{\theta JC}$ (Note 1)	$I_D$	$T_C = 25^\circ\text{C}$	207	A	
		$T_C = 85^\circ\text{C}$	149		
Power Dissipation $R_{\theta JC}$ (Note 1)	$P_D$	$T_C = 25^\circ\text{C}$	89.3	W	
		$T_C = 85^\circ\text{C}$			
Pulsed Drain Current	$t_p = 10\mu\text{s}$	$T_A = 25^\circ\text{C}$	$I_{DM}$	350	A
Current limited by package		$T_A = 25^\circ\text{C}$	$I_{Dmaxpkg}$	100	A
Operating Junction and Storage Temperature	$T_J, T_{STG}$	-55 to +150		$^\circ\text{C}$	
Source Current (Body Diode)	$I_S$	54		A	
Drain to Source dV/dt	dV/dt	6		V/ns	
Single Pulse Drain-to-Source Avalanche Energy ( $V_{DD} = 50$ V, $V_{GS} = 10$ V, $I_L = 50$ A <sub>pk</sub> , $L = 0.1$ mH, $R_G = 25$ $\Omega$ )	EAS	125		mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	$T_L$	260		$^\circ\text{C}$	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

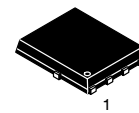
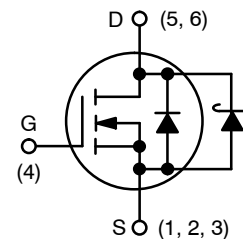


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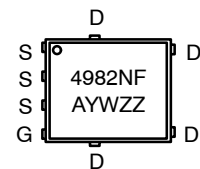
$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	$I_D$ MAX
30 V	1.3 m $\Omega$ @ 10 V	207 A
	1.9 m $\Omega$ @ 4.5 V	

### N-CHANNEL MOSFET



SO-8 FLAT LEAD  
CASE 488AA  
STYLE 1

### MARKING DIAGRAM



- A = Assembly Location
- Y = Year
- W = Work Week
- ZZ = Lot Traceability

### ORDERING INFORMATION

Device	Package	Shipping†
NTMFS4982NFT1G	SO-8FL (Pb-Free)	1500 / Tape & Reel
NTMFS4982NFT3G	SO-8FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# NTMFS4982NF

## THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	1.4	°C/W
Junction-to-Ambient – Steady State (Note 1)	$R_{\theta JA}$	46.6	
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	84.1	
Junction-to-Ambient – $t \leq 10$ sec	$R_{\theta JA}$	16.8	

1. Surface-mounted on FR4 board using 1 sq-in pad, 2 oz Cu.
2. Surface-mounted on FR4 board using the minimum recommended pad size of 100 mm<sup>2</sup>.

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1.0\text{ mA}$	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 10\text{ mA}$ , referenced to $25^\circ\text{C}$		15		mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$   $T_J = 25^\circ\text{C}$			500	μA
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			±100	nA

### ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 1.0\text{ mA}$	1.0	1.7	2.2	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$	$I_D = 10\text{ mA}$ , referenced to $25^\circ\text{C}$		5.0		mV/°C
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$   $I_D = 25\text{ A}$		0.95	1.3	mΩ
		$V_{GS} = 4.5\text{ V}$   $I_D = 25\text{ A}$		1.4	1.9	
Forward Transconductance	$g_{FS}$	$V_{DS} = 1.5\text{ V}, I_D = 15\text{ A}$		60		S

### CHARGES AND CAPACITANCES

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 15\text{ V}$		6000		pF
Output Capacitance	$C_{OSS}$			2400		
Reverse Transfer Capacitance	$C_{RSS}$			160		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 25\text{ A}$		40		nC
Threshold Gate Charge	$Q_{G(TH)}$			8.8		
Gate-to-Source Charge	$Q_{GS}$			15		
Gate-to-Drain Charge	$Q_{GD}$			12		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}, I_D = 25\text{ A}$		84		nC

### SWITCHING CHARACTERISTICS (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}, I_D = 25\text{ A}, R_G = 3\ \Omega$		17.2		ns
Rise Time	$t_r$			31.6		
Turn-Off Delay Time	$t_{d(OFF)}$			34.3		
Fall Time	$t_f$			12		
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}, I_D = 25\text{ A}, R_G = 3\ \Omega$		12.7		ns
Rise Time	$t_r$			20.4		
Turn-Off Delay Time	$t_{d(OFF)}$			38.6		
Fall Time	$t_f$			11.3		

3. Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Switching characteristics are independent of operating junction temperatures.

# NTMFS4982NF

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0\text{ V},$ $I_S = 2\text{ A}$	$T_J = 25^\circ\text{C}$		0.4	0.7	V
			$T_J = 125^\circ\text{C}$		0.32		
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0\text{ V}, dI_S/dt = 100\text{ A}/\mu\text{s},$ $I_S = 25\text{ A}$			58		ns
Charge Time	$t_a$				29		
Discharge Time	$t_b$				29		
Reverse Recovery Charge	$Q_{RR}$				71		

### PACKAGE PARASITIC VALUES

Source Inductance	$L_S$	$T_A = 25^\circ\text{C}$		0.65		nH
Drain Inductance	$L_D$			0.20		
Gate Inductance	$L_G$			1.5		
Gate Resistance	$R_G$			0.8		

3. Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

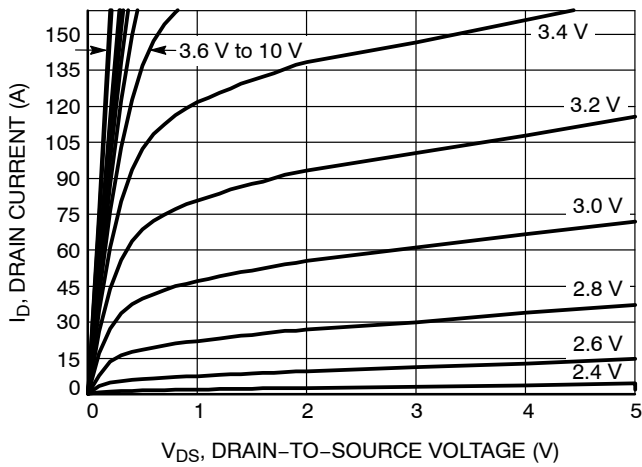


Figure 1. On-Region Characteristics

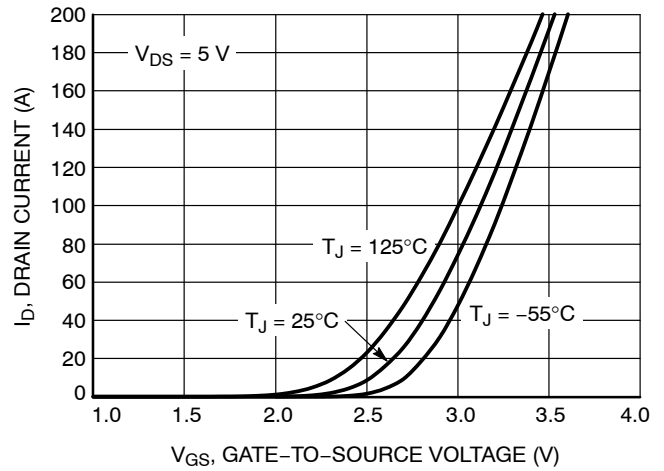


Figure 2. Transfer Characteristics

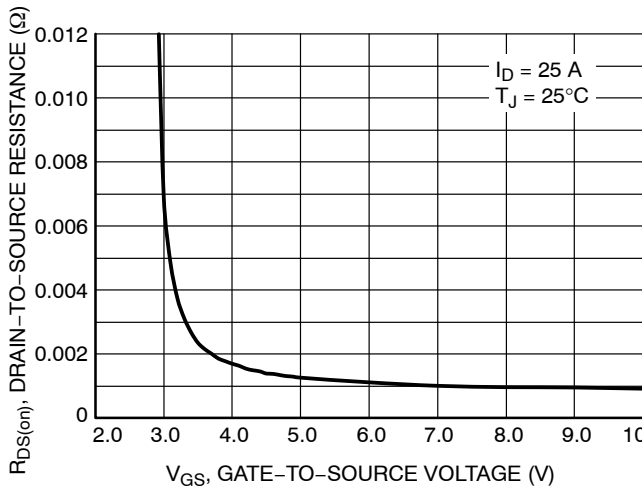


Figure 3. On-Resistance vs.  $V_{GS}$

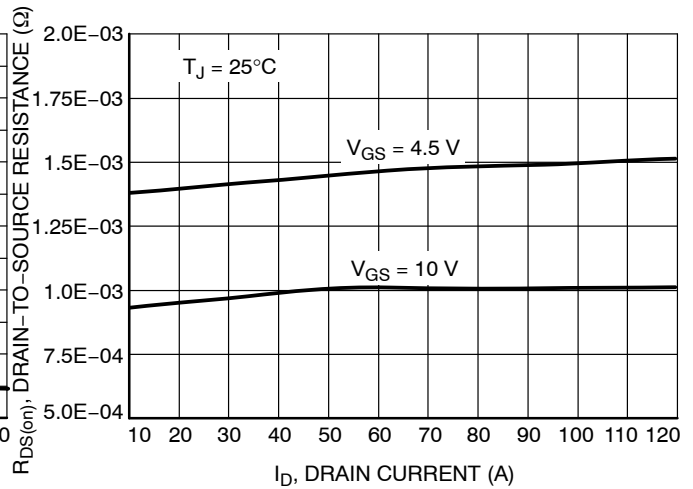


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

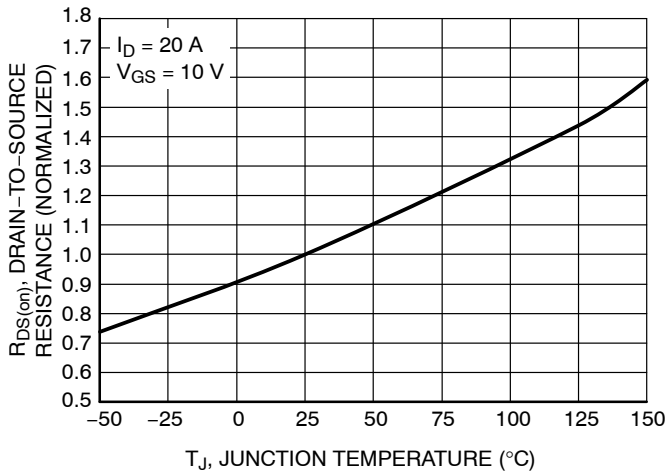


Figure 5. On-Resistance Variation with Temperature

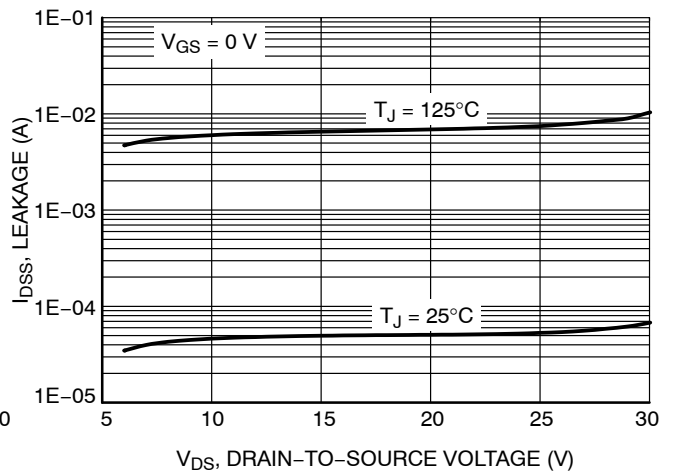


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

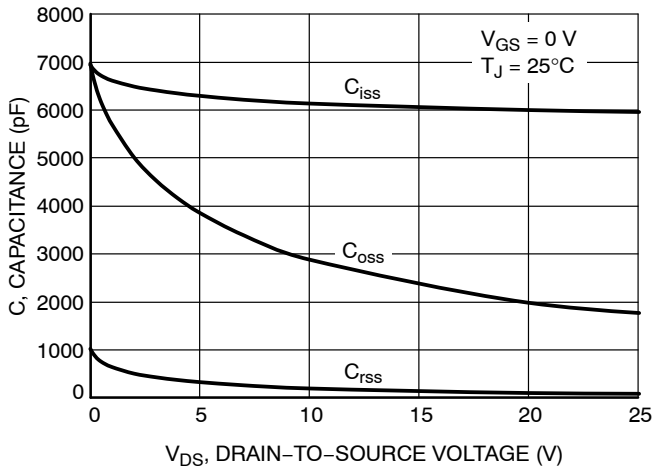


Figure 7. Capacitance Variation

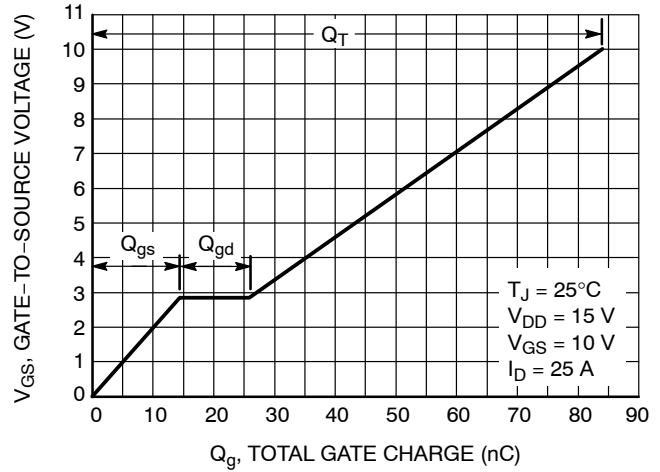


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

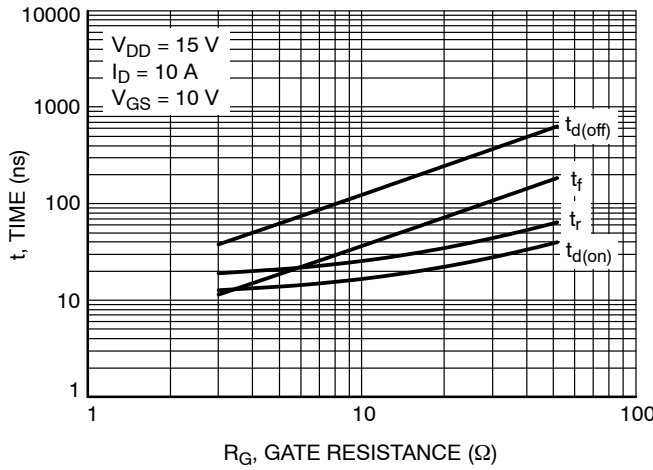


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

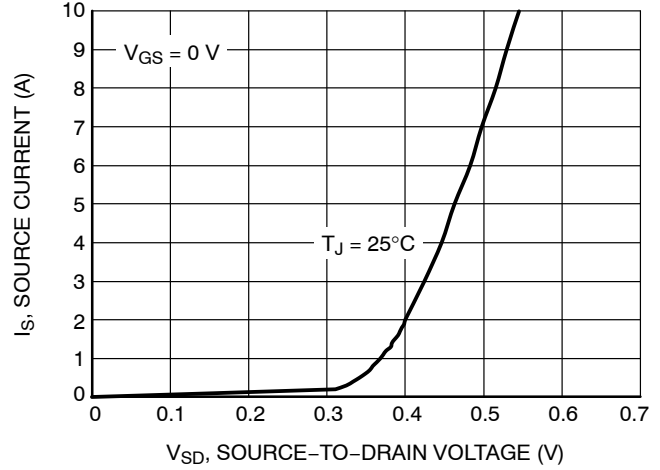


Figure 10. Diode Forward Voltage vs. Current

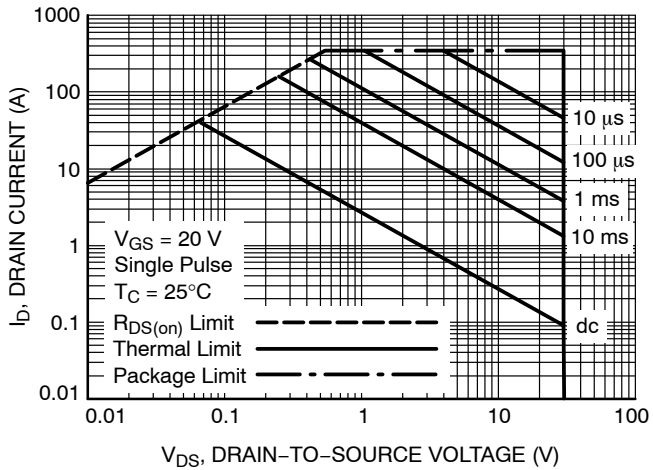


Figure 11. Maximum Rated Forward Biased Safe Operating Area

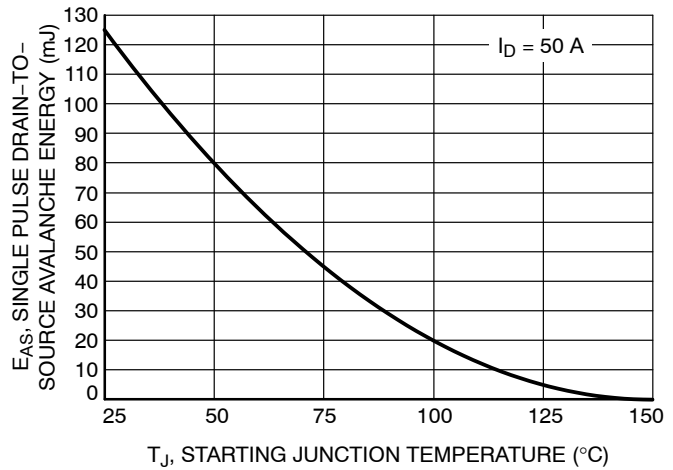


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

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## TYPICAL CHARACTERISTICS

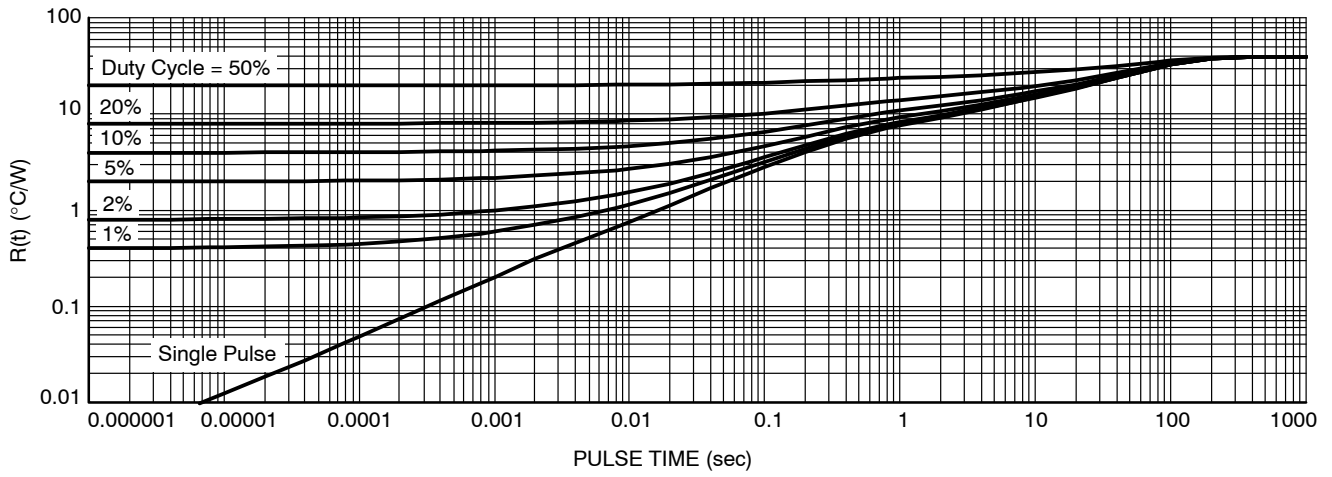


Figure 13. Thermal Response

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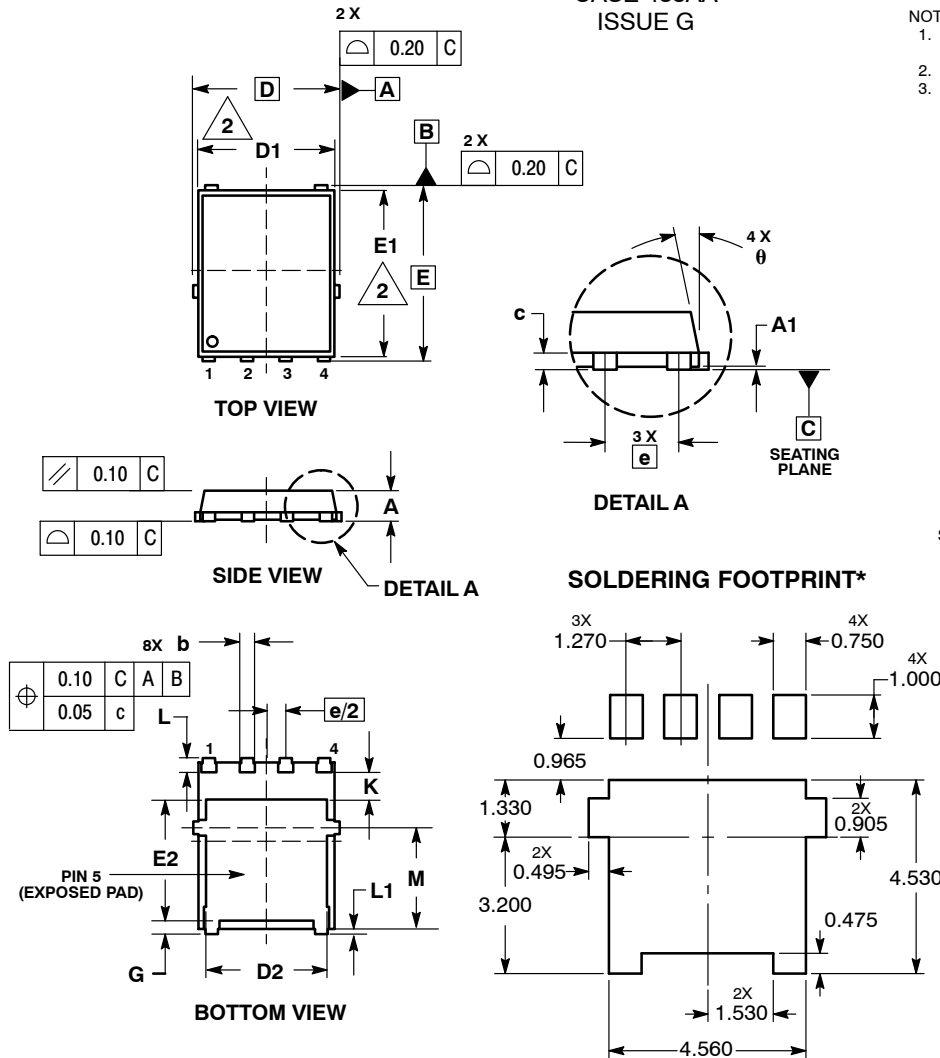
## PACKAGE DIMENSIONS

DFN5 5x6, 1.27P  
(SO-8FL)  
CASE 488AA  
ISSUE G

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.15 BSC		
D1	4.50	4.90	5.10
D2	3.50	---	4.22
E	6.15 BSC		
E1	5.50	5.80	6.10
E2	3.45	---	4.30
e	1.27 BSC		
G	0.51	0.61	0.71
K	1.20	1.35	1.50
L	0.51	0.61	0.71
L1	0.05	0.17	0.20
M	3.00	3.40	3.80
θ	0°	---	12°



STYLE 1:

1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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